

## ABSTRACT OF THE DISCLOSURE

A semiconductor device is disclosed, which  
comprise a first semiconductor chip where a  
semiconductor element is formed, a first connecting  
5 terminal arranged on a semiconductor element formation  
surface side in the first semiconductor chip and  
connected electrically to the semiconductor element, a  
conductive member buried in a through hole that goes  
through the first semiconductor chip, a second  
10 connecting terminal arranged on a back surface side of  
the semiconductor element formation surface in the  
first semiconductor chip, and connected electrically to  
the semiconductor element via the conductive member, a  
wiring substrate to which the first semiconductor chip  
15 is mounted, and a third connecting terminal at least  
portion of which is formed at a position corresponding  
to one of the first connecting terminal and the second  
connecting terminal, and which is electrically  
connected to the one of the first connecting terminal  
20 and the second connecting terminal.

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